

HSU276

Silicon Schottky Barrier Diode for Detector and Mixer

REJ03G0141-0700Z

(Previous: ADE-208-078F)

Rev.7.00 Nov.10.2003

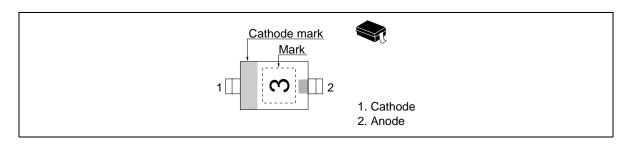
Features

- High forward current, Low capacitance.
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code	
HSU276	3	URP	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	3	V
Average rectified current	Io	30	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

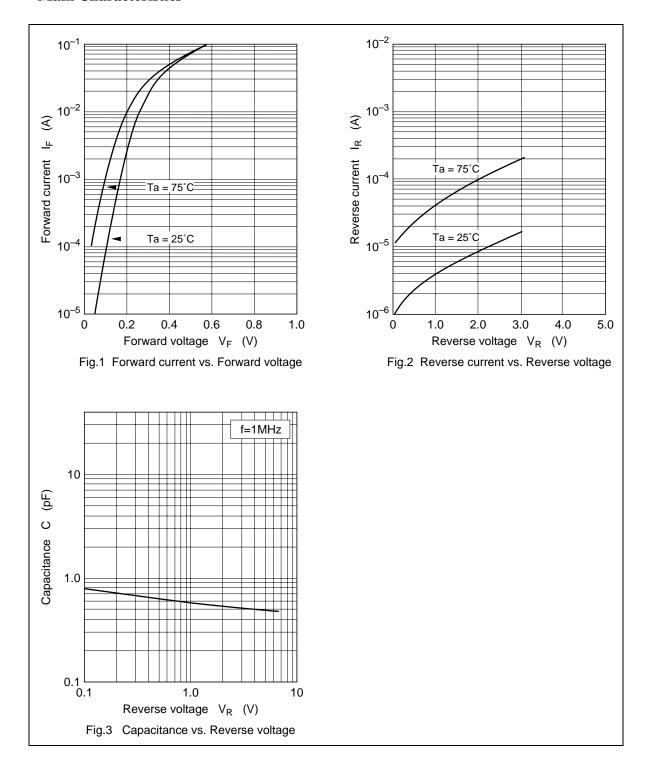
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

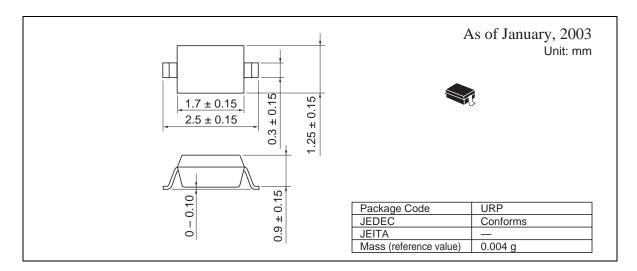
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V_R	3	_	_	V	I _R = 1 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 0.5 V
Forward current	I _F	35	_	_	mA	V _F = 0.5 V
Capacitance	С	_	_	0.85	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *1	_	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ; $I_R \ge 100 \mu A$ at $V_R = 0.5 V$

Main Characteristics



Package Dimensions



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